

2	ADD
3	VDD
4	NC
5	NC
6	NC
7	GND
8	RXINO-
9	RXINO+
10	GND
11	RXIN1-
12	RXIN1+
13	GND
14	RXIN2-
15	RXIN2+
16	GND
17	RXCLKIN-
18	RXCLK IN+
19	GND
20	RXIN3-
21	RXIN3+
22	GND
23	NC
24	NC
25	GND
26	NC
27	NC
28	NC
29	AVDD
30	GND
31	LED-
32	LED-
33	NC
34	NC
35	VGL
36	NC
37	NC
38	VGH
39	LED+

NO. Pin name

NOTES:

- 1. Display type:10.1"TFT
- 2. Viewing direction: Full viewing
- 3. Polarizer mode:Transmissive/normal black
- 4. Operation temperature:-20° C $^{\sim}$ +70° C
- 5. Storage temperature: -30° C~+80° C
- 6. Power supply voltage: 2.7V
- 7. Backlight: White (39LED) / Vf=9V (TYP.) If=260mA
- 8. Luminance: $300(\text{typ.}) \text{cd/m}^2$
- 9. Board Connector :196479-40041-3 or equivalent
- $10.\,\mathrm{ROHS}$ must be complied
- * Unspecification tolerance are $\pm 0.3 \mathrm{mm}$

Compliance: RohS III (2015/863/EU)

Tolerances:			Date 12/23	23 dr		VDD I CD I 4040 I VDC			
					YDP LCD I 1010 LVDS				
					1				
			kni	tter-s	witch	30 52	86	Page	
Renamed	04/24	dr				30 32	2 00		
Modifications	Date	Name							

PRODUCT SPECIFICATION

10.1" IPS TFT LCD MODULE MODEL: YDP LCD | 1010 LVDS Ver: 1.1



- < >> Preliminary Specification
- < >> Finally Specification

CUSTOMER'S APPROVAL				
CUSTOMER:				
SIG	NATURE:	DATE:		

APPROVED	РМ	PD	PREPARED
ВҮ	REVIEWED	REVIEWED	ВҮ
TFT S. G. H 20220629			TFT L. Q 20220629

Revision History

Revision	Date	Originator	Detail	Remarks
1.0	2022.03.16	LL	Initial Release	
1.1	2022.06.29	LQ	Modify Module Outline parameter Modify Outline Drawing(B)	P5 P27

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Outline Drawing1

1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	10.1"	
LCD type	IPS TFT	
Display Mode	Transmissive/ Normally Black	
Resolution	1280 RGB x 800	Pixels
View Direction	FULL VIEWING	Best Image
Module Outline	229.46(H) x149.10(V) x 3.0(T) (Note1)	mm
Active Area	216.96(H) x 135.60(V)	mm
Pixel Size	169.5 (H) x 169.5(V)	um
Pixel Arrangement	RGB Stripe	
Display Colors	16.7M	
Interface	LVDS interface	
With or Without Touch Panel	Without	
Operating Temperature	-20~+70	°C
Storage Temperature	-30~+80	•℃
Weight	TBD	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

GND=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VDD	2.3	3.6	V
Storage temperature	Тѕтс	-30	+80	°C
Operating temperature	T _{OP}	-20	+70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

ltem	Symbol	Min.	Тур.	Max.	Unit
	VDD	1	2.7	-	V
Supply Voltage/current	AVDD		TBD		V
Supply Voltage/current	VGH		TBD		V
	VGL		TBD	7 - BD BD BD	V
Input signal voltage	VCOM	-	TBD	-	V
Input logic high voltage	VIH	0.8*VDD	-	VDD	V
Input logic low voltage	VIL	0	-	0.2*VDD	V

Note 1: Typ. VCOM is only a reference value it must be optimized according to each LCM. Be sure to use VR.

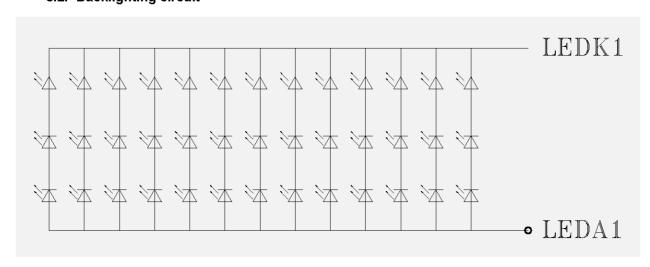
5. Backlight Characteristic

5.1. Backlight Characteristic

ltem	Symbol	Condition	Min	Тур	Max	Unit
Forward Voltage	VF	Ta=25 °C, I _F =20mA/LED	-	9.0	-	\
Forward Current	lF	Ta=25 °C, V _F =3.0V/LED	-	260	1	mΑ
Power dissipation	Pp		-	2340	-	mW
Uniformity	Avg		1	80	1	%
LED working life(25°C)	-		-	30,000	-	Hrs
Drive method	Constant current					
LED Configuration	39	White LEDs(13 LEDs in one	e string ar	d 3 groups	s in paralle	el)

Note: LED life time defined as follows: The final brightness is at 50% of original brightness. The environmental conducted under ambient air flow, at Ta=25 \pm 2 °C,60%RH \pm 5%, I_F=20mA/LED.

5.2. Backlighting circuit



6. Optical Characteristics

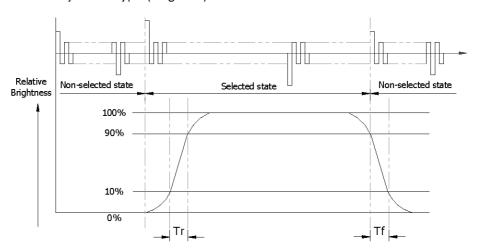
6.1. Optical Characteristics

 ${\rm Ta=25^{o}C},\ V_{\scriptscriptstyle DD}{\rm =2.7V}$

	Iton		Symbol	Condition	S	pecification	on	l lmi4
	lten	1	Symbol	Condition	Min.	Тур.	Max.	Unit
	Luminan	ce on						
(a)	$TFT(I_f = 20)$	mA/LED)	Lv	Normally viewing	240	300	-	cd/m²
ŏ	Contrast ratio	(See 6.3)	CR	angle	800	1000	-	
On (Transmissive Mode)	Response time (See 6.2)		TR+TF	θx = φy =0°	-	25	50	ms
nis:		Red	XR		-	TBD	-	
nsr	Chromaticity Transmissive (See 6.5)		YR		-	TBD	-	
Tra		nsmissive	Xg		1	TBD	1	
_ (.			Yg		1	TBD	1	
 			Хв		ı	TBD	ı	-
jij			Yв		-	TBD	=	
Backlight			Xw		ı	TBD	ı	
m		vville	Yw		ı	TBD	ı	
	Viewing	Horizontal	Өх+		75	85		
	Viewing Angle	Honzontal	Өх-	Center	75	85	-	Dea
	(See 6.4)	Vertical	φΥ+	CR≥10	75	85	-	Deg.
	(000 0.4)	vertical	φΥ-		75	85	-	
	NTSC Ratio	(Gamut)			-	TBD	-	%

6.2. Definition of Response Time

6.2.1 Normally Black Type (Negative)

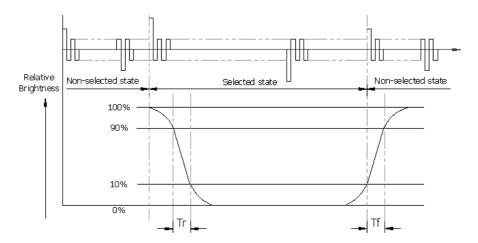


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2 Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

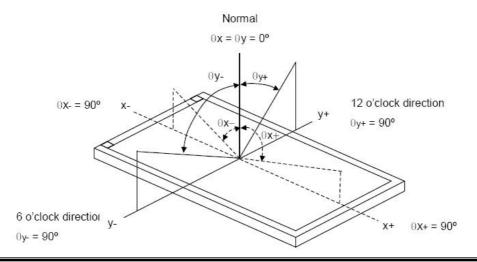
6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent	
Measuring Point Diameter	3mm//1mm	
Measuring Point Location	Active Area centre point	
Took mattern	A: All Pixels white	
Test pattern	B: All Pixel black	
Contrast setting	Maximum	

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles



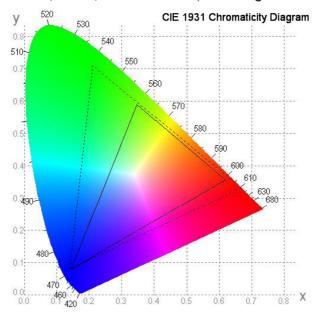
Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by $(x,\,y)$ on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

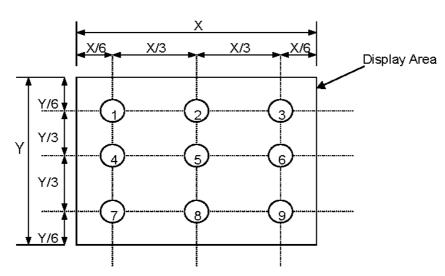


6.6. Definition of Surface Luminance, Uniformity and Transmittance

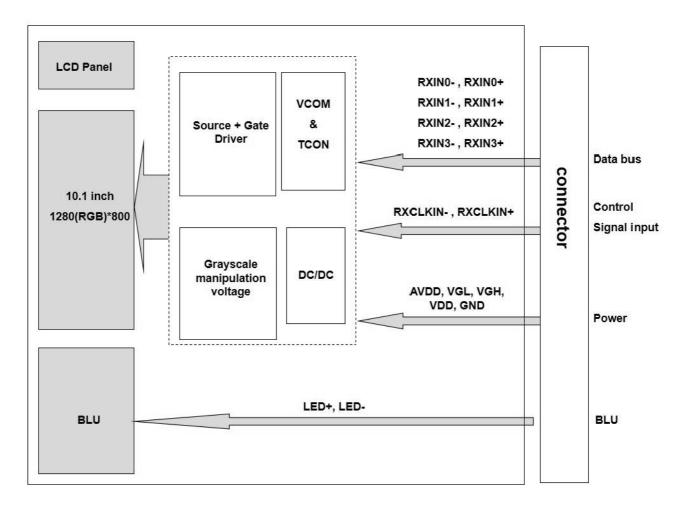
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1 Surface Luminance: L_V = average (L_{P1} : L_{P9})
- 6.6.2 Uniformity = Minimal (LP1:LP9) / Maximal (LP1:LP9) * 100%
- 6.6.3 Transmittance = L_V on LCD / L_V on Backlight * 100%

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply



8. Interface Pins Definition

CN1:Board Connector:196479-40041-3 or equivalent

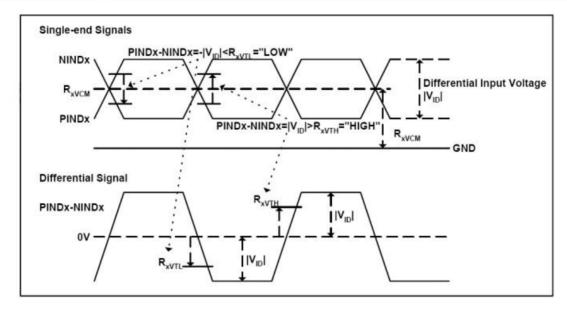
No.	Symbol	Function	Remark
1	NC	No connection	
2	VDD	Power Voltage for digital circuit	
3	VDD	Power Voltage for digital circuit	
4	NC	No connection	
5	NC	No connection	
6	NC	No connection	
7	GND	Ground	
8	RXIN0-	-LVDS differential data input	
9	RXIN0+	+LVDS differential data input	
10	GND	Ground	
11	RXIN1-	-LVDS differential data input	
12	RXIN1+	+LVDS differential data input	
13	GND	Ground	
14	RXIN2-	-LVDS differential data input	
15	RXIN2+	+LVDS differential data input	
16	GND	Ground	
17	RXCLKIN-	-LVDS differential clock input	LVDS
18	RXCLKIN+	+LVDS differential clock input	Clock
19	GND	Ground	
20	RXIN3-	-LVDS differential data input	
21	RXIN3+	+LVDS differential data input	
22	GND	Ground	
23	NC	No connection	
24	NC	No connection	
25	GND	Ground	
26	NC	No connection	
27	NC	No connection	
28	NC	No connection	
29	AVDD	Power for Analog Circuit	
30	GND	Ground	
31	LED-	LED Cathode	
32	LED-	LED Cathode	
33	NC	No connection	
34	NC	No connection	
35	VGL	Gate OFF Voltage	
36	NC	No connection	
37	NC	No connection	
38	VGH	Gate ON Voltage	

39	LED+	LED Anode	
40	LED+	LED Anode	

9. Timing Characteristics

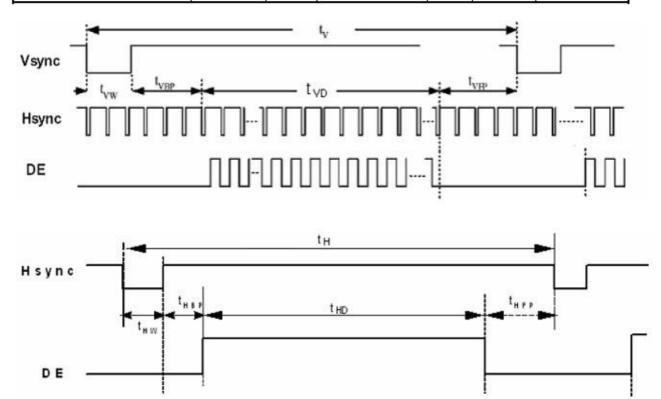
9.1. AC Electrical Characteristics

Parameter	Symbol		Values		Unit	Remark	
r diameter	Symbol	Min.	Тур.	Max.	Oiiit	Komark	
LVDS Differential input high Threshold voltage	R _{xVTH}	-	-	+100	mV	D =1 2\/	
LVDS Differential input low Threshold voltage	R _{xVTL}	-100	-	(4)	mV	-R _{XVCM} =1.2V	
LVDS Differential input common mode voltage	R _{xVCM}	0.7	-	1.6	٧		
LVDS Differential voltage	V _{ID}	200	-	600	mV		

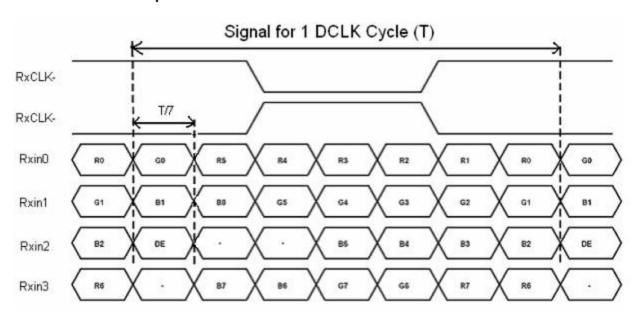


9.2. Timing Table

Parameter	Symbol	Min.	Values Typ.	Max.	Unit	Remark
Clock Frequency	1/Tc	68.9	71.1	73.4	MHz	Frame rate =60Hz
Horizontal display area	tHD		1280		Тс	
HS period time	tн	1410	1440	1470	Тс	
HS Width +Back Porch +Front Porch	tHW+ Thbp +tHFP	60	160	190	Тс	
Vertical display area	tvo		800	-	tн	
VS period time	tv	815	823	833	tH	
VS Width +Back Porch +Front Porch	tvw+ tvbp +tvFP	15	23	33	tн	

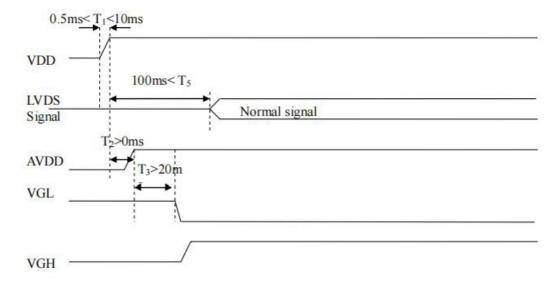


9.3. LVDS data input format

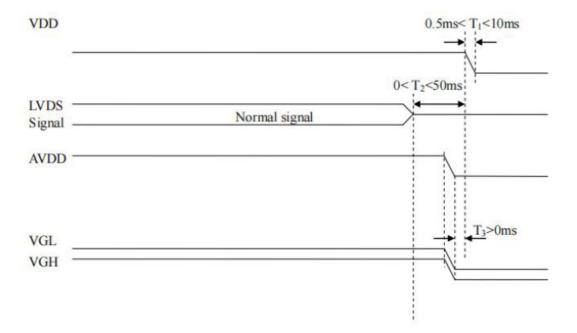


10. Power ON/OFF sequence

10.1.Power on



10.2. Power off



11. Quality Assurance

11.1. Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer

11.2. Standard for Quality Test

11.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

11.2.2. Sampling Criteria:

Visual inspection: AQL 1.5.

Electrical functional: AQL 0.65.

11.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

11.3. Nonconforming Analysis & Disposition

- 11.3.1. Nonconforming analysis:
 - 11.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.
 - 11.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
 - 11.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.
- 11.3.2. Disposition of nonconforming:
 - 11.3.2.1. Non-conforming product over PPM level will be replaced.
 - 11.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

11.4. Agreement Items

Shall negotiate with customer if the following situation occurs:

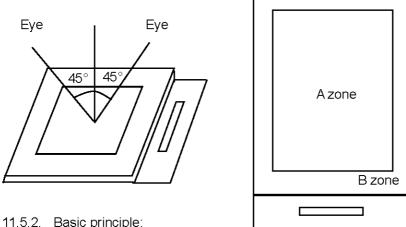
- 11.4.1. There is any discrepancy in standard of quality assurance.
- 11.4.2. Additional requirement to be added in product specification.
- 11.4.3. Any other special problem.

11.5. Standard of the Product Visual Inspection

- 11.5.1. Appearance inspection:
 - 11.5.1.1. The inspection must be under illumination about 1000 1500 lx, and the distance of view must be at 30cm ± 2cm and Telecommunication function detection, ambient light less than 300lux.

11.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

11.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,



11.5.2. Basic principle:

11.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened. 11.5.2.2. New item must be added on time when it is necessary.

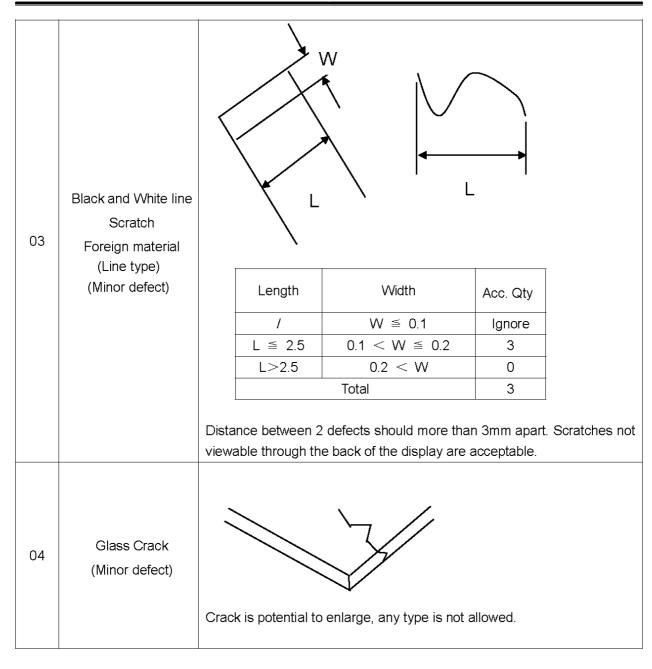
11.6.Inspection Specification

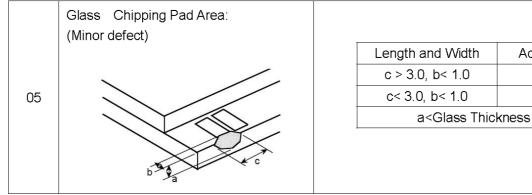
No.	ltem	Criteria (Unit: mm)			
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	φ= (a + b) /2	Size φ≤0.20 0.20<φ≤0. 0.50<φ	1g	oc. Qty gnore N≤3 0
		Distance between 2 defects s	hould more than	5mm apart.	
		Dright dot	Display Area	Total	
		Bright dot	N≤2	N ≤ 2	Note1
		Dark dot	N≤4	N≤4	Note
02	Electrical Defect	Total dot	N≤4	N≤4	
02	(Minor defect)	Mura	Not visible thro filters	_	Note 2
		Remark: 1. Bright dot caused by scratc	h and foreign ob	oject accords to	item 1.

Acc. Qty

1

3





	Glass Chipping Rear of Pad Area:				
	(Minor defect)				
			Length and Width	Acc. Qty	
	_		c > 3.0, b< 1.0	1	
06			c< 3.0, b< 1.0	2	
			c< 3.0, b< 0.5	4	
			 a <glass td="" thicl<=""><td></td><td></td></glass>		
	C	'			
	b ga				
	Glass Chipping Except Pad Area:				
	(Minor defect)				
			Length and Width	Acc. Qty	
			c > 3.0, b< 1.0	1	
07			c< 3.0, b< 1.0	2	
			c< 3.0, b< 0.5	4	
	b		a <glass td="" thicl<=""><td></td><td></td></glass>		
		'	a -01a55 111101	(TICSS	
	a				
	Glass Corner Chipping:				
	(Minor defect)				
			Length and Width	Acc. Qty	
			c < 3.0, b< 3.0	Ignore	
08			a <glass td="" thicl<=""><td></td><td></td></glass>		
		'			
	back				
	Glass Burr:				
	(Minor defect)	[Length	Acc. Qty	
			F < 1.0	Ignore	
		'		-	
		Glass	burr don't affect as	semble and me	odule
		dimen			
09	F				
	_				
	F				
	I .				

10	FPC Defect: (Minor defect)	-	10.1 Dent, pinhole (w: circuitry width.) 10.2 Open circuit is 10.3 No oxidation, o		ortion.
11	Bubble on Polarizer (Minor defect)		Diameter φ≤0.30 0.30 <φ≤0.50 0.50 < φ	Acc. Qty Ignore N≤2 N=0	
12	Dent on Polarizer (Minor defect)		Diameter φ≤0.25 0.25 <φ≤0.50 0.50 < φ	Acc. Qty Ignore N≤4 None	
13	Bezel	13.1 No rust, distortion on the Bezel. 13.2 No visible fingerprints, stains or other contamination.			
14	PCB	14.1 No distortion or contamination on PCB terminals. 14.2 All components on PCB must same as documented on the BOM/component layout. 14.3 Follow IPC-A-600F.			n the
15	Soldering	Follow IPC-A-610	OC standard		
16	Electrical Defect (Major defect)	The below defects must be rejected. 16.1 Missing vertical / horizontal segment, 16.2 Abnormal Display. 16.3 No function or no display. 16.4 Current exceeds product specifications. 16.5 LCD viewing angle defect. 16.6 No Backlight. 16.7 Dark Backlight. 16.8 Touch Panel no function.			

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

11.7. Classification of Defects

- 11.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 11.7.2. Two minor defects are equal to one major in lot sampling inspection.

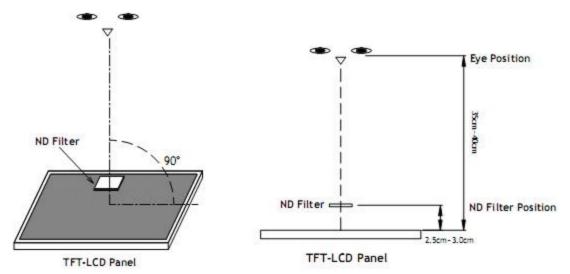
11.8. Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

11.9. Packing

- 11.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 11.9.2. Modules inside package box should have compliant mark.
- 11.9.3. All direct package materials shall offer ESD protection.

Note1:Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixelarea.



Bright dot:The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is 350mm ±50mm.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

12. Reliability Specification

No	ltem	Condition	Quantity	Criteria
1	High Temperature Operating	70℃ , 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity Storage	40℃, 90%RH, 96Hrs	2	GB/T2423.3 -2016
4	High Temperature Storage	80℃, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test Storage	-0℃, 60min~50℃, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X,Y,Z 30 min for each direction.	-	GB/T5170.14 -2009
0	Electrical Otatic Discharge	Air:±4KV 150pF/330 Ω 5 times	2	GB/T17626.2
8	Electrical Static Discharge	Contact: ±2KV 150pF/330 Ω 5 times	2	-2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

13. Precautions and Warranty

13.1. Safety

- 13.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 13.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

13.2. Handling

- 13.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 13.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

13.3. Storage

- 13.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 13.3.2. Strong light exposure causes degradation of polarizer and color filter.

13.4. Metal Pin (Apply to Products with Metal Pins)

- 13.4.1. Pins of LCD and Backlight
 - 13.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering
 - 13.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

Maximum Solder Temperature: 370 ℃

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20 °C

Typical Soldering Time: ≤3s

13.4.1.3. Solder Wetting



Solder Pin Lead
Not Recommended

13.4.2. Pins of EL

- 13.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.
- 13.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.
- 13.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

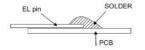
Recommended Solder Temperature: 270~290 ℃

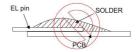
Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

- 13.4.2.4. No horizontal press on the EL leads during soldering.
- 13.4.2.5. 180° bend EL leads three times is not allowed.

13.4.2.6. Solder Wetting





Recommended

Not Recommended

13.4.2.7. The type of the solder iron:





Recommended

Not Recommended

13.4.2.8. Solder Pad



13.5. Operation

- 13.5.1. Do not drive LCD with DC voltage
- 13.5.2. Response time will increase below lower temperature
- 13.5.3. Display may change color with different temperature
- 13.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 13.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 13.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 13.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 13.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.

13.6.Static Electricity

- 13.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 13.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 13.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

13.7.Limited Warranty

- 13.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 13.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used
- 13.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

14. Packaging

TBD